

Materials Declaration

|                 |          |
|-----------------|----------|
| Package         | QSOP_EP  |
| Body Size/Pitch | 150 mils |
| LeadCount       | 16       |
| Option          | Pb-free  |

| Molding Compound  |               |            |        |
|-------------------|---------------|------------|--------|
| Substance         | % of Compound | Weight (g) | PPM    |
| Silica            | 75.00         | 3.23 E-02  | 415760 |
| Resin             | 22.20         | 9.56 E-03  | 123065 |
| Antimony Trioxide | 2.00          | 8.61 E-04  | 11087  |
| Brominated Resin  | 0.80          | 3.44 E-04  | 4435   |
| Subtotal          | 100           | 4.30 E-02  | 554346 |

| Leadframe  |                |            |        |
|------------|----------------|------------|--------|
| Substance  | % of Leadframe | Weight (g) | PPM    |
| Copper     | 97.5           | 2.99 E-02  | 385470 |
| Iron       | 2.35           | 7.21 E-04  | 9291   |
| Zinc       | 0.12           | 3.68 E-05  | 474    |
| Phosphorus | 0.03           | 9.21 E-06  | 119    |
| Subtotal   | 100            | 3.07 E-02  | 395354 |

| Internal Leadframe Plating |              |            |      |
|----------------------------|--------------|------------|------|
| Substance                  | % of Plating | Weight (g) | PPM  |
| Silver                     | 100          | 4.45 E-04  | 5731 |

| External Leadframe Plating |              |            |       |
|----------------------------|--------------|------------|-------|
| Substance                  | % of Plating | Weight (g) | PPM   |
| Tin                        | 100          | 1.43 E-03  | 18421 |

| Bond Wires |           |            |      |
|------------|-----------|------------|------|
| Substance  | % of Wire | Weight (g) | PPM  |
| Gold       | 99.99     | 4.20 E-04  | 5409 |

| Chip          |           |            |       |
|---------------|-----------|------------|-------|
| Substance     | % of Chip | Weight (g) | PPM   |
| Doped Silicon | 100       | 1.30 E-03  | 16701 |

| Die Attach          |                 |            |      |
|---------------------|-----------------|------------|------|
| Substance           | % of Die Attach | Weight (g) | PPM  |
| Silver              | 73.40           | 2.30 E-04  | 2964 |
| Epoxy Resin         | 18.35           | 5.75 E-05  | 741  |
| Metal oxide         | 2.75            | 8.62 E-06  | 111  |
| Amine               | 2.75            | 8.62 E-06  | 111  |
| Gamma Butyrolactone | 2.75            | 8.62 E-06  | 111  |
| Subtotal            | 100.00          | 3.14 E-04  | 4039 |

| Molding Compound                      |              |                          |
|---------------------------------------|--------------|--------------------------|
| Substance                             | PPM          | Method                   |
| Lead                                  | Not Detected | Draft IEC62321. ICP-OES. |
| Cadmium                               | Not Detected | Draft IEC62321. ICP-OES. |
| Mercury                               | Not Detected | Draft IEC62321. ICP-OES. |
| Chromium+6                            | Not Detected | Draft IEC62321. UV-VIS.  |
| Polybrominated biphenyls (PBB)        | Not Detected | Draft IEC62321. GC-MSD.  |
| Polybrominated Diphenyl Ethers (PBDE) | Not Detected | Draft IEC62321. GC-MSD.  |

| Die Attach Paste                      |              |                          |
|---------------------------------------|--------------|--------------------------|
| Substance                             | PPM          | Method                   |
| Lead                                  | Not Detected | Draft IEC62321. ICP-OES. |
| Cadmium                               | Not Detected | Draft IEC62321. ICP-OES. |
| Mercury                               | Not Detected | Draft IEC62321. ICP-OES. |
| Chromium+6                            | Not Detected | Draft IEC62321. UV-VIS.  |
| Polybrominated biphenyls (PBB)        | Not Detected | Draft IEC62321. GC-MSD.  |
| Polybrominated Diphenyl Ethers (PBDE) | Not Detected | Draft IEC62321. GC-MSD.  |

Package Totals

| Weight (g) | PPM     |
|------------|---------|
| 7.77 E-02  | 1000000 |

Note: The information provided in this declaration are true to the best of ADI's knowledge  
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability  
any inaccuracy of such information.



ADI Proprietary

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|-----------------|----------|
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| LeadCount       | 16       |
| Option          | with Pb  |

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| Subtotal          | 100           | 4.30 E-02  | 554346 |

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|------------|----------------|------------|--------|
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| Subtotal   | 100            | 3.07 E-02  | 395354 |

| Internal Leadframe Plating |              |            |      |
|----------------------------|--------------|------------|------|
| Substance                  | % of Plating | Weight (g) | PPM  |
| Silver                     | 100          | 4.45 E-04  | 5731 |

| External Leadframe Plating |              |            |       |
|----------------------------|--------------|------------|-------|
| Substance                  | % of Plating | Weight (g) | PPM   |
| Tin                        | 85           | 1.22 E-03  | 15658 |
| Lead                       | 15           | 2.15 E-04  | 2763  |
| Subtotal                   | 100          | 1.43 E-03  | 18421 |

| Bond Wires |           |            |      |
|------------|-----------|------------|------|
| Substance  | % of Wire | Weight (g) | PPM  |
| Gold       | 99.99     | 4.20 E-04  | 5409 |

| Chip          |           |            |       |
|---------------|-----------|------------|-------|
| Substance     | % of Chip | Weight (g) | PPM   |
| Doped Silicon | 100       | 1.30 E-03  | 16701 |

| Die Attach          |                 |            |      |
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| Subtotal            | 100             | 3.14 E-04  | 4039 |

| Package Totals |         |
|----------------|---------|
| Weight (g)     | PPM     |
| 7.77 E-02      | 1000000 |

| Molding Compound                      |              |                          |
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| Substance                             | PPM          | Method                   |
| Lead                                  | Not Detected | Draft IEC62321. ICP-OES. |
| Cadmium                               | Not Detected | Draft IEC62321. ICP-OES. |
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| Cadmium                               | Not Detected | Draft IEC62321. ICP-OES. |
| Mercury                               | Not Detected | Draft IEC62321. ICP-OES. |
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